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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XF

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc620a-04e-so

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FIGURE 3-1: BLOCK DIAGRAM



4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM. The Special Function Registers can be classified into two sets (core and peripheral). The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS ⁽¹⁾
Bank 0											
00h	INDF	Addressin register)	ig this locat	on uses co	ntents of FS	SR to addre	ess data me	mory (not a	a physical	XXXX XXXX	XXXX XXXX
01h	TMR0	Timer0 Mo	odule's Reg	ister						xxxx xxxx	uuuu uuuu
02h	PCL	Program (Counter's (F	PC) Least S	Significant B	yte				0000 0000	0000 0000
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h	FSR	Indirect da	ata memory	address po	ointer					xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h-09h	Unimplemented									_	_
0Ah	PCLATH	—	—	—	Write buffe	er for upper	5 bits of pr	ogram coui	nter	0 0000	0 0000
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0	-0
0Dh-1Eh	Unimplemented									_	_
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00 0000	00 0000
Bank 1											
80h	INDF	Addressin register)	g this locat	ion uses co	ntents of FS	SR to addre	ess data me	mory (not a	a physical	xxxx xxxx	xxxx xxxx
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program (Counter's (F	PC) Least S	ignificant B	yte				0000 0000	0000 0000
83h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h	FSR	Indirect da	ata memory	address po	ointer					xxxx xxxx	uuuu uuuu
85h	TRISA	-	-	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h-89h	Unimplemented									_	_
8Ah	PCLATH	-	-	—	Write buffe	er for upper	5 bits of pr	ogram coui	nter	0 0000	0 0000
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0	-0
8Dh	Unimplemented									_	_
8Eh	PCON	_	_	_	_	—	—	POR	BOR	0x	uq
8Fh-9Eh	Unimplemented								-	_	_
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16C62X

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown,

 ${\rm q}$ = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

2: IRP & RP1 bits are reserved; always maintain these bits clear.

TABLE 5-1:PORTA FUNCTIONS

Name	Bit #	Buffer Type	Function
RA0/AN0	bit0	ST	Input/output or comparator input
RA1/AN1	bit1	ST	Input/output or comparator input
RA2/AN2/VREF	bit2	ST	Input/output or comparator input or VREF output
RA3/AN3	bit3	ST	Input/output or comparator input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0 or comparator output. Output is open drain type.

Legend: ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
05h	PORTA		_		RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA	_	_	_	TRISA 4	TRISA 3	TRISA 2	TRISA 1	TRISA 0	1 1111	1 1111
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by PORTA.

6.3 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that there is only one prescaler available which is mutually exclusive between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.



FIGURE 6-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER

6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on-the-fly" during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

	-	
1.BCF	STATUS, RPO	;Skip if already in ;Bank 0
2.CLRWDT		;Clear WDT
3.CLRF	TMR0	;Clear TMR0 & Prescaler
4.BSF	STATUS, RPO	;Bank 1
5.MOVLW	'00101111'b;	;These 3 lines (5, 6, 7)
6.MOVWF	OPTION	;are required only if ;desired PS<2:0> are
7.CLRWDT		;000 or 001
8.MOVLW	'00101xxx'b	;Set Postscaler to
9.MOVWF	OPTION	;desired WDT rate
10.BCF	STATUS, RPO	;Return to Bank 0

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 6-2:

CHANGING PRESCALER (WDT→TIMER0)

	•	
CLRWDT		;Clear WDT and
		;prescaler
BSF	STATUS, RPO	
MOVLW	b'xxxx0xxx'	;Select TMR0, new
		prescale value and
		, plock gourgo
		,CIOCK SOULCE
MOVWF	OPTION REG	
BCF	STATUS, RPO	

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0	Timer0 module register								uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	_	_		TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by TMR0 module.

7.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 7-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator

mode is changed, the comparator output level may not be valid for the specified mode change delay shown in Table 12-2.

Note: Comparator interrupts should be disabled during a Comparator mode change otherwise a false interrupt may occur.





The code example in Example 7-1 depicts the steps required to configure the comparator module. RA3 and RA4 are configured as digital output. RA0 and RA1 are configured as the V- inputs and RA2 as the V+ input to both comparators.

EXAMPLE 7-1: INITIALIZING COMPARATOR MODULE

MOVLW	0x03	;Init comparator mode
MOVWF	CMCON	;CM<2:0> = 011
CLRF	PORTA	;Init PORTA
BSF	STATUS, RPO	;Select Bank1
MOVLW	0x07	;Initialize data direction
MOVWF	TRISA	;Set RA<2:0> as inputs
		;RA<4:3> as outputs
		;TRISA<7:5> always read `0'
BCF	STATUS, RPO	;Select Bank 0
CALL	DELAY 10	;10µs delay
MOVF	CMCON,F	;Read CMCONtoend change condition
BCF	PIR1,CMIF	;Clear pending interrupts
BSF	STATUS, RPO	;Select Bank 1
BSF	PIE1,CMIE	;Enable comparator interrupts
BCF	STATUS, RPO	;Select Bank 0
BSF	INTCON, PEIE	;Enable peripheral interrupts
BSF	INTCON, GIE	;Global interrupt enable

7.2 Comparator Operation

A single comparator is shown in Figure 7-2 along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 7-2 represent the uncertainty due to input offsets and response time.

7.3 Comparator Reference

An external or internal reference signal may be used depending on the comparator Operating mode. The analog signal that is present at VIN- is compared to the signal at VIN+, and the digital output of the comparator is adjusted accordingly (Figure 7-2).





7.3.1 EXTERNAL REFERENCE SIGNAL

When external voltage references are used, the comparator module can be configured to have the comparators operate from the same or different reference sources. However, threshold detector applications may require the same reference. The reference signal must be between VSs and VDD, and can be applied to either pin of the comparator(s).

7.3.2 INTERNAL REFERENCE SIGNAL

The comparator module also allows the selection of an internally generated voltage reference for the comparators. Section 10, Instruction Sets, contains a detailed description of the Voltage Reference Module that provides this signal. The internal reference signal is used when the comparators are in mode CM<2:0>=010 (Figure 7-1). In this mode, the internal voltage reference is applied to the VIN+ pin of both comparators.

TABLE 7-1 :	REGISTERS ASSOCIATED WITH COMPARATOR MODULE
--------------------	--

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
1Fh	CMCON	C2OUT	C10UT			CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1		CMIF		_	_			_	-0	-0
8Ch	PIE1	_	CMIE	_	_	_	_	_	_	-0	-0
85h	TRISA		_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as "0"

-

EXAMPLE 8-1: VOLTAGE REFERENCE CONFIGURATION

MOVLW	0x02	; 4 Inputs Muxed
MOVWF	CMCON	; to 2 comps.
BSF	STATUS, RPO	; go to Bank 1
MOVLW	0x0F	; RA3-RA0 are
MOVWF	TRISA	; inputs
MOVLW	0xA6	; enable VREF
MOVWF	VRCON	; low range
		; set VR<3:0>=6
BCF	STATUS, RPO	; go to Bank O
CALL	DELAY10	; 10µs delay

8.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 8-1) keep VREF from approaching VSS or VDD. The voltage reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The tested absolute accuracy of the voltage reference can be found in Table 12-2.

8.3 Operation During SLEEP

When the device wakes up from SLEEP through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the voltage reference should be disabled.

8.4 Effects of a RESET

A device RESET disables the voltage reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

8.5 Connection Considerations

The voltage reference module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the voltage reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the voltage reference output for external connections to VREF. Figure 8-2 shows an example buffering technique.

FIGURE 8-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE

TABLE 8-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR	Value On All Other RESETS
9Fh	VRCON	VREN	VROE	VRR		VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C10UT	_	-	CIS	CM2	CM1	CM0	00 0000	00 0000
85h	TRISA	_	_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Note: - = Unimplemented, read as "0"

9.5.1 RB0/INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before reenabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP and Figure 9-18 for timing of wakeup from SLEEP through RB0/INT interrupt.

9.5.2 TMR0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 6.0.

9.5.3 PORTB INTERRUPT

An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note:	If a change on the I/O pin should occur
	when the read operation is being executed
	(start of the Q2 cycle), then the RBIF
	interrupt flag may not get set.

9.5.4 COMPARATOR INTERRUPT

See Section 7.6 for complete description of comparator interrupts.



FIGURE 9-16: INT PIN INTERRUPT TIMING

9.7 Watchdog Timer (WDT)

The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the CLKIN pin. That means that the WDT will run, even if the clock on the OSC1 and OSC2 pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming the configuration bit WDTE as clear (Section 9.1).

9.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see

DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

9.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.



FIGURE 9-17: WATCHDOG TIMER BLOCK DIAGRAM

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS
2007h	Config. bits	—	BODEN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0	—	—
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: Shaded cells are not used by the Watchdog Timer.

Note: – = Unimplemented location, read as "0"

+ = Reserved for future use

10.1 Instruction Descriptions

ADDLW	Add Literal and W									
Syntax:	[<i>label</i>] ADDLW k									
Operands:	$0 \leq k \leq 255$									
Operation:	$(W) + k \to (W)$									
Status Affected:	C, DC, Z									
Encoding:	11 111x kkkk kkkk									
Description:	added to the eight bit literal 'k' and the result is placed in the W register.									
Cycles:	1									
Example	ADDLW 0x15									
	Before Instruction W = 0x10 After Instruction W = 0x25									

ANDLW	AND Literal with W									
Syntax:	[<i>label</i>] ANDLW k									
Operands:	$0 \le k \le 255$									
Operation:	(W) .AND. (k) \rightarrow (W)									
Status Affected:	Z									
Encoding:	11 1001 kkkk kkkk									
Description:	The contents of W register are AND'ed with the eight bit literal 'k'. The result is placed in the W register.									
Words:	1									
Cycles:	1									
Example	ANDLW 0x5F									
	Before Instruction W = 0xA3 After Instruction W = 0x03									
ANDWF	AND W with f									

Add W and f									
[<i>label</i>] ADDWF f,d									
$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$									
(W) + (f) \rightarrow (dest)									
C, DC, Z									
00 0111 dfff ffff									
Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.									
1									
1									
ADDWF FSR, O									
Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0xD9 FSR = 0xC2									

ANDWF	AND W with f									
Syntax:	[label] ANDWF f,d									
Operands:	$0 \le f \le 127$ $d \in [0,1]$									
Operation:	(W) .AND. (f) \rightarrow (dest)									
Status Affected:	Z									
Encoding:	00 0101 dfff ffff									
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.									
Words:	1									
Cycles:	1									
Example	ANDWF FSR, 1									
	Before Instruction W = 0x17 FSR = 0xC2 After Instruction W = 0x17 FSR = 0x02									

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BCF	Bit Clear f	BTFSC	Bit Test, Skip if Clear			
Syntax:	[<i>label</i>]BCF f,b	Syntax:	[<i>label</i>]BTFSC f,b			
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$	Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$			
Operation:	$0 \rightarrow (f \le b >)$	Operation:	skip if (f) = 0			
Status Affected:	None	Status Affected:	None			
Encoding:	01 00bb bfff ffff	Encoding:	01 10bb bfff ffff			
Description:	Bit 'b' in register 'f' is cleared.	Description:	If bit 'b' in register 'f' is '0', then the			
Words:	1		next instruction is skipped.			
Cycles:	1		tion fetched during the current			
Example	BCF FLAG_REG, 7		instruction execution is discarded, and a NOP is executed instead, making this a two-cycle instruction.			
	Before Instruction FLAG REG = 0xC7					
	After Instruction	Words:	1			
	FLAG REG = 0x47	Cycles:	1(2)			
		Example	HERE BTFSC FLAG,1			
BSF	Bit Set f		TRUE • DE			
Syntax:	[<i>label</i>]BSF f,b		•			
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$		Before Instruction PC = address HERE			
Operation:	$1 \rightarrow (f \le b >)$		After Instruction			
Status Affected:	None		PC = address TRUE			
Encoding:	01 01bb bfff ffff		if FLAG<1>=1,			
Description:	Bit 'b' in register 'f' is set.		PC = address FALSE			
Words:	1					
Cycles:	1					
Example	BSF FLAG_REG, 7					

Before Instruction FLAG_REG = 0x0A After Instruction

FLAG_REG = 0x8A

11.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI C compilers for Microchip's PIC17CXXX and PIC18CXXX family of microcontrollers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian manages the creation and modification of library files of pre-compiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.5 MPLAB C30 C Compiler

The MPLAB C30 C compiler is a full-featured, ANSI compliant, optimizing compiler that translates standard ANSI C programs into dsPIC30F assembly language source. The compiler also supports many command-line options and language extensions to take full advantage of the dsPIC30F device hardware capabilities, and afford fine control of the compiler code generator.

MPLAB C30 is distributed with a complete ANSI C standard library. All library functions have been validated and conform to the ANSI C library standard. The library includes functions for string manipulation, dynamic memory allocation, data conversion, time-keeping, and math functions (trigonometric, exponential and hyperbolic). The compiler provides symbolic information for high level source debugging with the MPLAB IDE.

11.6 MPLAB ASM30 Assembler, Linker, and Librarian

MPLAB ASM30 assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 compiler uses the assembler to produce it's object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- · Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- · MPLAB IDE compatibility

11.7 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC hosted environment by simulating the PICmicro series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user defined key press, to any pin. The execution can be performed in Single-Step, Execute Until Break, or Trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and MPLAB C18 C Compilers, as well as the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent, economical software development tool.

11.8 MPLAB SIM30 Software Simulator

The MPLAB SIM30 software simulator allows code development in a PC hosted environment by simulating the dsPIC30F series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user defined key press, to any of the pins.

The MPLAB SIM30 simulator fully supports symbolic debugging using the MPLAB C30 C Compiler and MPLAB ASM30 assembler. The simulator runs in either a Command Line mode for automated tasks, or from MPLAB IDE. This high speed simulator is designed to debug, analyze and optimize time intensive DSP routines.

11.20 PICDEM 18R PIC18C601/801 Demonstration Board

The PICDEM 18R demonstration board serves to assist development of the PIC18C601/801 family of Microchip microcontrollers. It provides hardware implementation of both 8-bit Multiplexed/De-multiplexed and 16-bit Memory modes. The board includes 2 Mb external FLASH memory and 128 Kb SRAM memory, as well as serial EEPROM, allowing access to the wide range of memory types supported by the PIC18C601/801.

11.21 PICDEM LIN PIC16C43X Demonstration Board

The powerful LIN hardware and software kit includes a series of boards and three PICmicro microcontrollers. The small footprint PIC16C432 and PIC16C433 are used as slaves in the LIN communication and feature on-board LIN transceivers. A PIC16F874 FLASH microcontroller serves as the master. All three micro-controllers are programmed with firmware to provide LIN bus communication.

11.22 PICkit[™] 1 FLASH Starter Kit

A complete "development system in a box", the PICkit FLASH Starter Kit includes a convenient multi-section board for programming, evaluation, and development of 8/14-pin FLASH PIC[®] microcontrollers. Powered via USB, the board operates under a simple Windows GUI. The PICkit 1 Starter Kit includes the user's guide (on CD ROM), PICkit 1 tutorial software and code for various applications. Also included are MPLAB[®] IDE (Integrated Development Environment) software, software and hardware "Tips 'n Tricks for 8-pin FLASH PIC[®] Microcontrollers" Handbook and a USB Interface Cable. Supports all current 8/14-pin FLASH PIC microcontrollers, as well as many future planned devices.

11.23 PICDEM USB PIC16C7X5 Demonstration Board

The PICDEM USB Demonstration Board shows off the capabilities of the PIC16C745 and PIC16C765 USB microcontrollers. This board provides the basis for future USB products.

11.24 Evaluation and Programming Tools

In addition to the PICDEM series of circuits, Microchip has a line of evaluation kits and demonstration software for these products.

- KEELOQ evaluation and programming tools for Microchip's HCS Secure Data Products
- CAN developers kit for automotive network applications
- Analog design boards and filter design software
- PowerSmart battery charging evaluation/ calibration kits
- IrDA[®] development kit
- microID development and rfLab[™] development software
- SEEVAL[®] designer kit for memory evaluation and endurance calculations
- PICDEM MSC demo boards for Switching mode power supply, high power IR driver, delta sigma ADC, and flow rate sensor

Check the Microchip web page and the latest Product Line Card for the complete list of demonstration and evaluation kits.

12.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings †

Ambient Temperature under bias	40° to +125°C
Storage Temperature	65° to +150°C
Voltage on any pin with respect to Vss (except VDD and MCLR)	-0.6V to VDD +0.6V
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on MCLR with respect to Vss (Note 2)	0 to +14V
Voltage on RA4 with respect to Vss	8.5V
Total power Dissipation (Note 1)	1.0W
Maximum Current out of Vss pin	
Maximum Current into VDD pin	
Input Clamp Current, Iк (Vi <0 or Vi> VDD)	±20 mA
Output Clamp Current, IOK (Vo <0 or Vo>VoD)	±20 mA
Maximum Output Current sunk by any I/O pin	
Maximum Output Current sourced by any I/O pin	25 mA
Maximum Current sunk by PORTA and PORTB	
Maximum Current sourced by PORTA and PORTB	
Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD - \sum IOH} + \sum	$\{(VDD-VOH) \times IOH\} + \sum (VOI \times IOL).$

2: Voltage spikes below Vss at the MCLR pin, inducing currents greater than 80 mA, may cause latchup. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the MCLR pin rather than pulling this pin directly to Vss.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

				Standard Operating Conditions (unless otherwise stated)							
PIC16CR	62XA-	04	Opera	ating te	empera	ature -	\leq TA \leq +85°C for industrial and				
PIC16CR	62XA-	20					0°C	\leq TA \leq +70°C for commercial and			
						-4	40°C	\leq TA \leq +125°C for extended			
			Standard Operating Conditions (unless otherwise stated)								
	DESYA	04	Opera	ating te	empera	ature -4	40°C	\leq TA \leq +85°C for industrial and			
FICTULCI		-04		$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial							
				-40°C \leq TA \leq +125°C for extended							
Param.	Sym	Characteristic	Min	Тур†	Max	Units		Conditions			
No.											

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in k Ω .

5: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.5 DC CHARACTERISTICS: PIC16C620A/C621A/C622A-40⁽⁷⁾ (Commercial) PIC16CR620A-40⁽⁷⁾ (Commercial)

DC CHARACTERISTICS				Standard Operating Conditions (unless otherwise stated)Operating temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial								
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions					
D001	Vdd	Supply Voltage	3.0		5.5	V	Fosc = DC to 20 MHz					
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾		1.5*	_	V	Device in SLEEP mode					
D003	VPOR	VDD start voltage to ensure Power-on Reset	_	Vss		V	See section on Power-on Reset for details					
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05 *			V/ms	See section on Power-on Reset for details					
D005	VBOR	Brown-out Detect Voltage	3.65	4.0	4.35	V	BOREN configuration bit is cleared					
D010	IDD	Supply Current ^(2,4)	—	1.2	2.0	mA	Fosc = 4 MHz, VDD = 5.5V, WDT disabled, XT Osc mode, (Note 4)*					
			—	0.4	1.2	mA	Fosc = 4 MHz, VDD = 3.0V, WDT disabled, XT Osc mode. (Note 4)					
			—	1.0	2.0	mA	Fosc = 10 MHz, VDD = 3.0V, WDT disabled, HS Osc mode. (Note 6)					
			—	4.0	6.0	mA	Fosc = 20 MHz, VDD = 4.5V, WDT disabled,					
			—	4.0	7.0	mA	Fosc = 20 MHz, VDD = 5.5V, WDT disabled*,					
			—	35	70	μA	Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP Osc mode					
D020	IPD	Power Down Current ⁽³⁾		_	2.2	μA	VDD = 3.0V					
			—	—	5.0	μA	VDD = 4.5V*					
			—	—	9.0	μA	$V_{DD} = 5.5V$					
D 000			_	_	15	μΑ						
D022	AIWDI	WD1 Current ^(*)		6.0	10	μΑ	VDD = 4.0V (125°C)					
D022A	AIBOR	Brown-out Reset Current ⁽⁵⁾	_	75	125	μΑ	$\frac{(123)}{123}$ Of BOD enabled, VDD = 5.0V					
D023		Comparator Current for each Comparator ⁽⁵⁾	—	30	60	μA	VDD = 4.0V					
D023A	Δ IVREF	VREF Current ⁽⁵⁾	_	80	135	μA	VDD = 4.0V					
	Δ IEE Write	Operating Current	_		3	mA	Vcc = 5.5V, SCL = 400 kHz					
	$\Delta \text{IEE} \ \text{Read}$	Operating Current	—		1	mA						
	ΔIEE	Standby Current	—		30	μA	Vcc = 3.0V, EE VDD = Vcc					
	ΔIEE	Standby Current	—		100	μA	VCC = 3.0V, EE VDD = VCC					
1A	Fosc	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures					
		XC Oscillator Operating Frequency	0	—	4	IVIHZ M⊔⊸						
		HS Oscillator Operating Frequency	0		- - 20	MHz	All temperatures					

These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption. The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD, MCLR = VDD; WDT enabled/disabled as specified.
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP

mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.
For RC OSC configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/ 2REXT (mA) with REXT in kΩ.

5: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

7: See Section 12.1 and Section 12.3 for 16C62X and 16CR62X devices for operation between 20 MHz and 40 MHz for valid modified characteristics.

PIC16C62X

12.9 Timing Diagrams and Specifications

FIGURE 12-12: EXTERNAL CLOCK TIMING



TABLE 12-3: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency ⁽¹⁾	DC	—	4	MHz	XT and RC Osc mode, VDD=5.0V
			DC	_	20	MHz	HS Osc mode
			DC	_	200	kHz	LP Osc mode
		Oscillator Frequency ⁽¹⁾	DC	—	4	MHz	RC Osc mode, VDD=5.0V
			0.1	_	4	MHz	XT Osc mode
			1	_	20	MHz	HS Osc mode
			DC	_	200	kHz	LP Osc mode
1	Tosc	External CLKIN Period ⁽¹⁾	250	_		ns	XT and RC Osc mode
			50	_		ns	HS Osc mode
			5	—	_	μS	LP Osc mode
		Oscillator Period ⁽¹⁾	250	—		ns	RC Osc mode
			250	_	10,000	ns	XT Osc mode
			50	_	1,000	ns	HS Osc mode
			5	_		μS	LP Osc mode
2	Тсү	Instruction Cycle Time ⁽¹⁾	1.0	Fosc/4	DC	μS	Tcys=Fosc/4
3*	TosL,	External Clock in (OSC1) High or	100*	_		ns	XT oscillator, Tosc L/H duty cycle
	TosH	Low Time	2*	_		μS	LP oscillator, Tosc L/H duty cycle
			20*	_		ns	HS oscillator, Tosc L/H duty cycle
4*	TosR,	External Clock in (OSC1) Rise or	25*	_		ns	XT oscillator
	TosF	Fall Time	50*	—	—	ns	LP oscillator
			15*	_	_	ns	HS oscillator

2: * These parameters are characterized but not tested.

3: † Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



FIGURE 12-15: BROWN-OUT RESET TIMING



TABLE 12-5:RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP
TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	2000	—		ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	_	1024 Tosc	_		Tosc = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	Tioz	I/O hi-impedance from MCLR low		—	2.0	μS	
35	TBOR	Brown-out Reset Pulse Width	100*	_		μs	$3.7V \leq V\text{DD} \leq 4.3V$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.